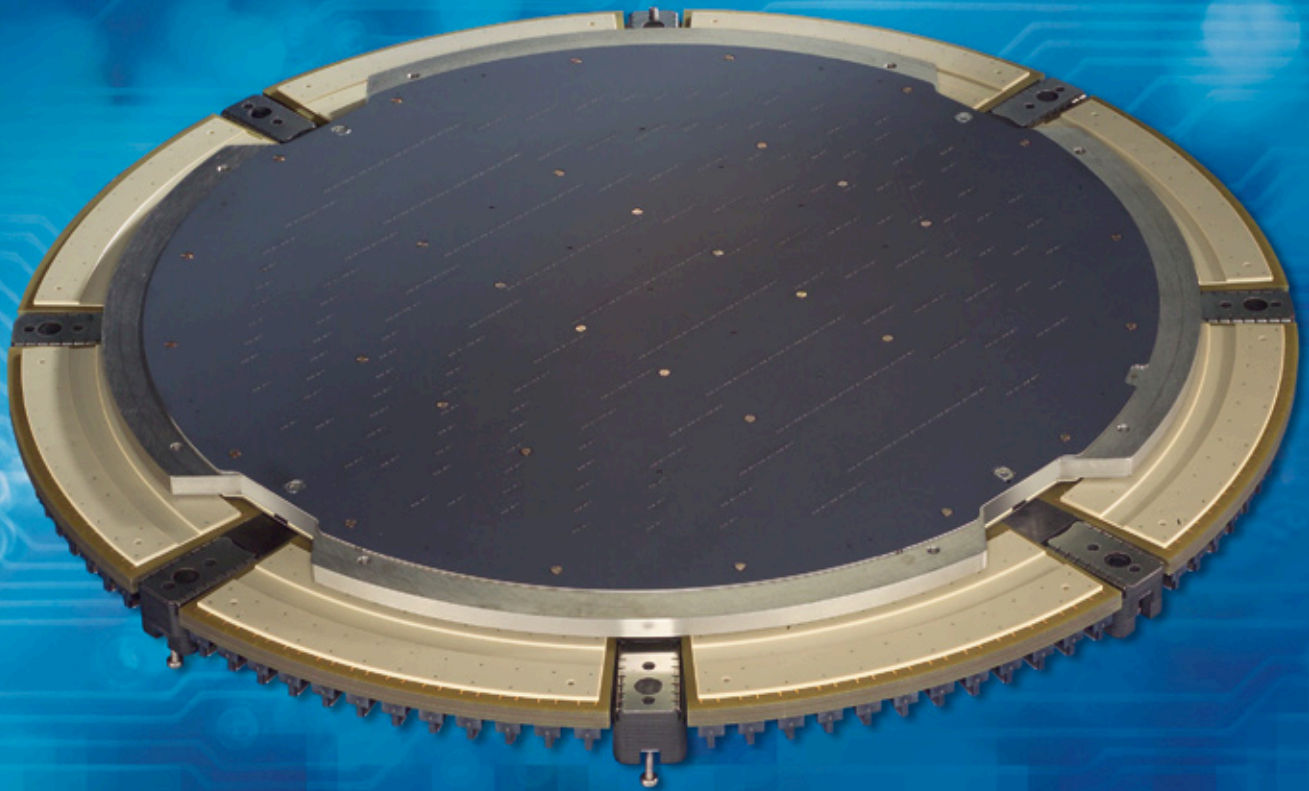


# ViProbe® XXL 300

Wafer Test Probecard



**FEINMETALL**

Contact technologies for electronics

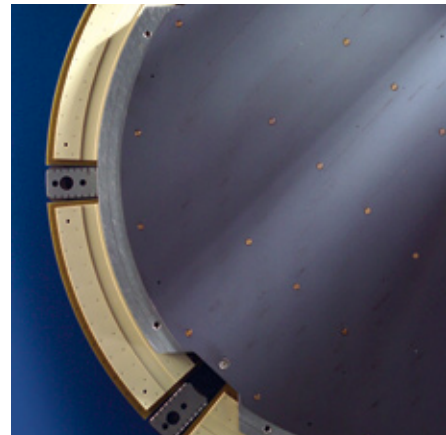
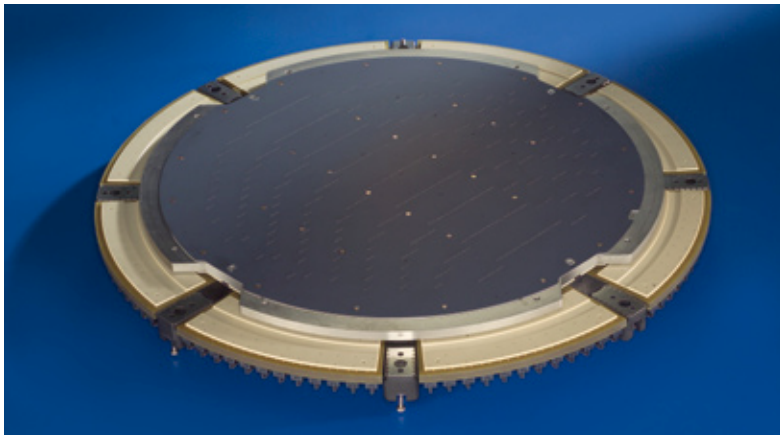


## ViProbe® XXL 300

FEINMETALL ViProbe® XXL-Series represents the leading technology in high parallel wafer probing.

Our ViProbe® Type XXL 300 is designed for a 1-, 2- or more touch-down solution at 300 mm wafer with an active test area of 310 mm. Major application is for memory wafer test

or other advanced multiple DIE test application. ViProbe® XXL products are based on Direct Attach ViProbe® Technology and currently available for pad pitches down to 80 µm. ViProbe® XXL products provide the capability for substantial time- and cost-savings in wafer testing.



- Memory Chip Application
- High Parallel Probing
- Active Area Ø 310 mm
- up to 25.000 Test Points
- min. Pad Pitch 80 µm
- 2.5 MIL Beam
- Contact Force ~ 6,5 cN / BEAM
- Low Contact Force ~ 5,5 cN / BEAM
- Tester: Advantest 5375 / 5377 / Verigy 5400
- Prober: TSK UF 3000 / TEL P12

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